

78. (New) The process of claim 77 further comprising depositing one or more additional dyad, each additional dyad comprising an additional conductive barrier material layer and a transparent layer selected from the group consisting of a layer of organic polymer, a layer of dielectric, a layer of metal and a layer of conductive oxide.

REMARKS

Claims 1-38 have been cancelled. New claims 39-78 have been added.

Support for the newly added claims may be found in the Second Substitute Specification. Specific details are listed in the Table below.

New Claim	Original Claim	Support
39-65		Original claims 1-38
66		p. 12, lines 10-15
67		p. 4 lines 11-16
68		p. 4, lines 2-3 and p.14, line 22-23
69		p. 9, lines 33-35
70		p. 13, lines 13-16
71		p. 13, lines 13-16 and lines 23-29
72		p. 4, lines 23-24
73		Figure 1
74		p. 5, lines 32-35
75		Figure 1
76		p. 9, lines 8-23
77		Figure 1
78		p. 5, lines 32-35

Examination and consideration of the application is requested.

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Respectfully submitted,

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